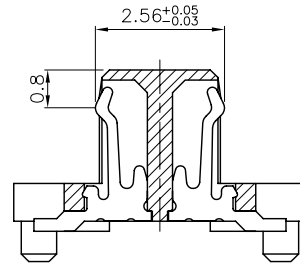
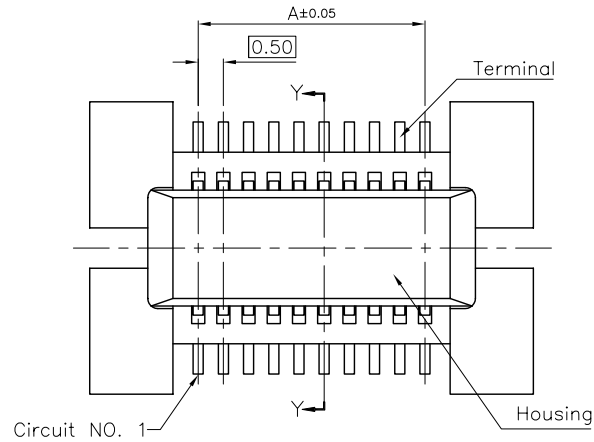
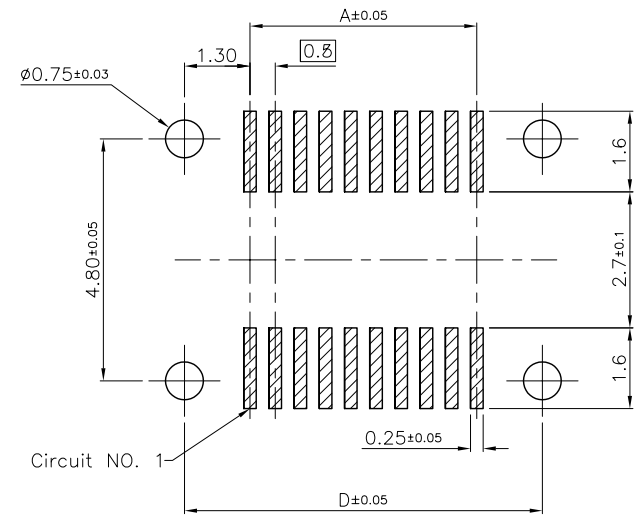


NP0524-S10P-xxx-LF
LEADFREE
Rohs Compliant

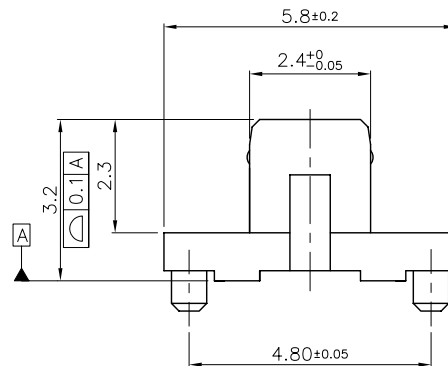
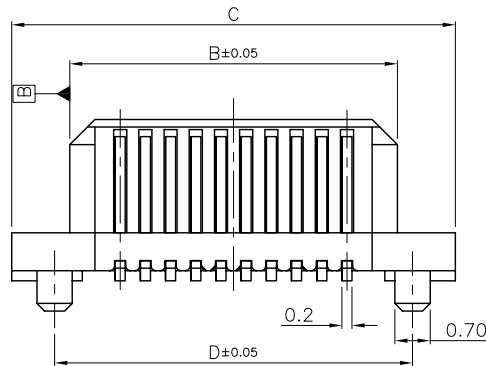
- NOTES:
- MATERIAL:
HOUSING:HIGH TEMP THERMO PLASTIC
TERMINAL:COPPER ALLOY
 - PLATING:
TERMINAL:
(1):50u"min NICKEL OVERALL GOLD FLASH ALLOVER.
(2):50u"min NICKEL OVERALL,
120u" MIN. TIN LEAD ON SOLDER TAIL,
3u" MIN. GOLD ON CONTACT AREA.
 - COPLANARITY 0.1 MM MAX. BASE ON DATUM A
 - TRUE POSITION 0.1 MM MAX. BAES ON DATUM B



SEC. Y-Y



RECOMMENDED PC BOARD PATTERN DIM. (REF.)



CKT	DIM A	DIM B	DIM C	DIM D
16	3.5	5.5	7.8	6.1
20	4.5	6.5	8.8	7.1
30	7.0	9.0	11.3	9.6
40	9.5	11.5	13.8	12.1
50	12.0	14.0	16.3	14.6
60	14.5	16.5	18.8	17.1
70	17.0	19.0	21.3	19.6
80	19.5	21.5	23.8	22.1
100	24.5	26.5	28.8	27.1
120	29.5	31.5	33.8	32.1

MORETHANALL
CONNECTORS
ASSEMBLIES

PART NO. NP05 24-S10 P-xxx

DWG NO. NP05 24-S10 P-xxx

FILE NO.

UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION

TOLERANCES ARE

.X ± 0.2
.XX ± 0.1
.XXX ±
AWG

DESCRIP TION:

AREA

REVISIONS

HK

DATE

煜倫股份有限公司